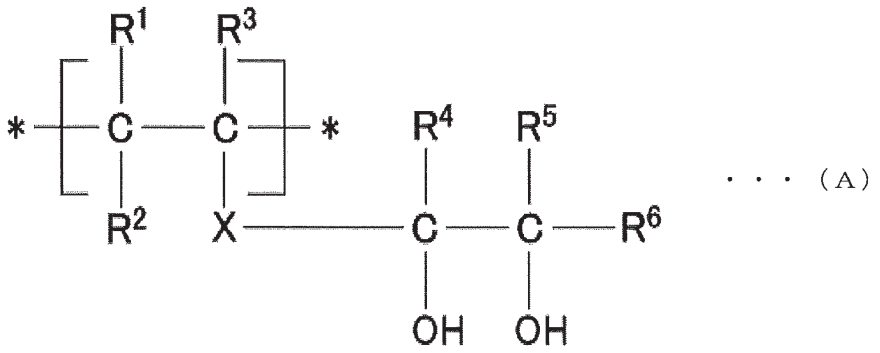
following general formula, (A), polymerized with vinylpyrrolidone:

[Chem. 1]



· · · (A)

Here, each of R^1, R^2 and R^3 independently indicates a hydrogen atom or an organic group, X indicates a single bond or a bonding chain, and each of R^4, R^5 and R^6 independently indicates a hydrogen atom or an organic group.

In one aspect, there is provided a method of polishing a silicon wafer, comprising polishing a silicon wafer using the polishing composition described herein.

EFFECTS OF THE INVENTION

[0014] The present invention provides a polishing composition that can further reduce minute defects and haze on the semiconductor wafer after polishing and is highly capable of hydophilizing the semiconductor wafer.

EMBODIMENTS FOR CARRYING OUT THE INVENTION

[0015] To solve the above-stated problems, the present inventor conducted various investigations, and discovered that using a water-soluble polymer constituted by a copolymer with a vinyl alcohol–based resin having a 1,2-diol structural unit polymerized with vinylpyrrolidone provides a polishing composition that improves the ability to provide wettability, which has been a problem with conventional techniques using PVA–PVP and, as a whole, has a good balance.

[0016] The present invention was made based on these findings. A polishing composition according to an embodiment of the present invention will now be described in detail.

[0017] A polishing composition according to an embodiment of the present

invention includes: an abrasive; a basic compound; and a water-soluble polymer, the water-soluble polymer being a copolymer with a vinyl alcohol–based resin having a 1,2-diol structural unit polymerized with vinylpyrrolidone.